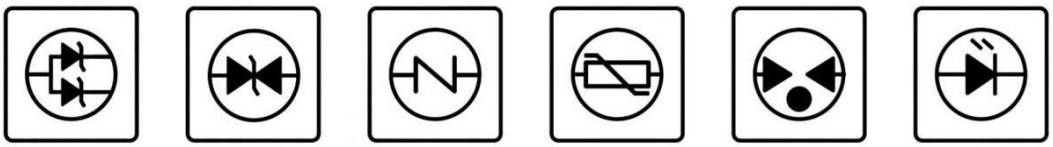
MSKSEMI 美森科
SEMICONDUCTOR



SS32FA-MS THRU SS310FA-MS

Product specification

SS32FA-MS THRU SS310FA-MS

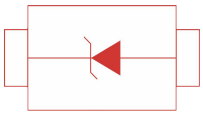
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Metal silicon junction,majority carrier conduction
- Low power loss,high efficiency
- High forward surge current capability
- High temperature soldering guaranteed: 250°C/10 seconds,0.375(9.5mm) lead length, 5 lbs. (2.3kg) tension

MECHANICAL DATA

- Case: JEDEC SOD-123FL molded plastic body over passivated junction
- Terminals : Plated axial leads, solderable per MIL-STD-750,Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight:0.0007 ounce, 0.02 grams

Reference News

SOD-123FL	Schematic Diagram
	

Marking

SS32FA-MS	SS33FA-MS	SS34FA-MS	SS35FA-MS	SS36FA-MS
K32	K33	K34	K35	K36
SS37FA-MS	**SS38FA-MS**	**SS39FA-MS**	**SS310FA-MS**	
K37	K38	K39	K310	

Maximum Ratings and Electrical Characteristics

TA = 25℃ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SS32 FA-MS	SS33 FA-MS	SS34 FA-MS	SS35 FA-MS	SS36 FA-MS	SS37 FA-MS	SS38 FA-MS	SS39 FA-MS	SS310 FA-MS	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	70	80	90	100	Volts
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	49	56	63	70	Volts
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	70	80	90	100	Volts
Maximum average forward rectified current	$I_{(AV)}$	3.0									Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	80.0									Amps
Maximum instantaneous forward voltage at 3.0A	V_F	0.52	0.55		0.70		0.85				Volts
Maximum DC reverse current at rated DC blocking voltage T_A=25℃	I_R	0.5									mA
T_A=100℃		20.0					10.0				
Operating junction temperature range	T_J	-50 to +125					-50 to +150				℃
Storage temperature range	T_{STG}	-50 to +150									℃

RATINGS AND CHARACTERISTIC CURVES SS32FA-MS THRU SS310-MS

FIG. 1- FORWARD CURRENT DERATING CURVE

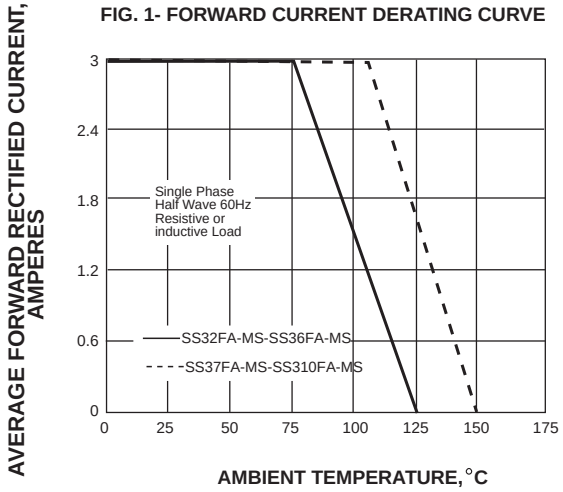


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

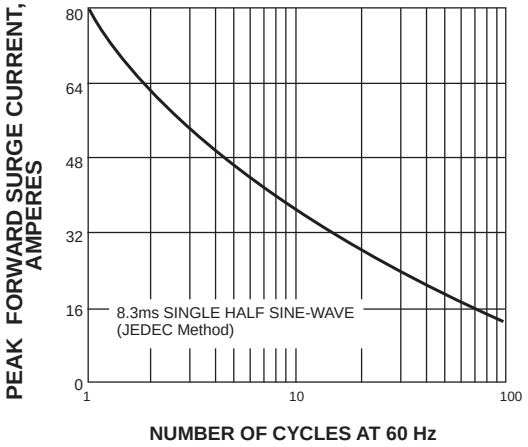


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

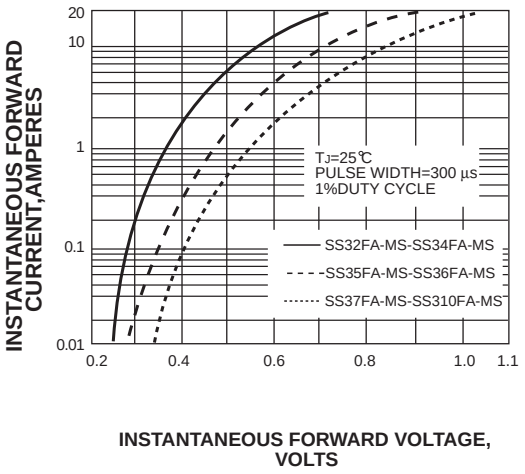
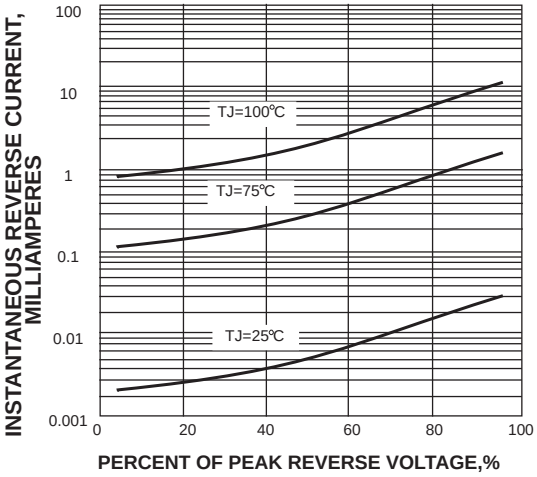
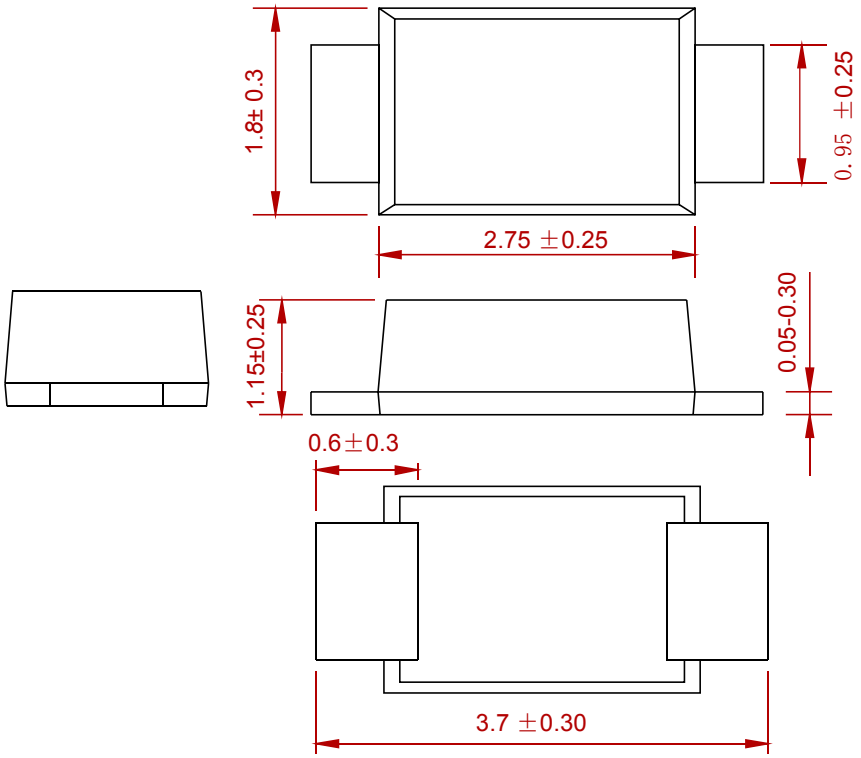


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

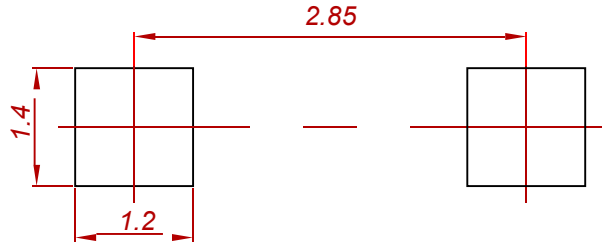


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SS32FA-MS THRU SS310FA-MS	SOD-123FL	3000

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